FRALOCK[®] Leading the Way in Advanced Materials Solutions

HEATERS FOR SEMICONDUCTOR MANUFACTURING

Fralock provides custom-engineered heaters for critical in-chamber, testing, and packaging processes used in a variety of both front and back-end semiconductor manufacturing applications. We two material types, providing you with options to choose the ideal material solution for your requirements.

Ceramic Heaters are designed for extremely rapid heating and cooling to maximize efficiency in production.

Polyimide Heaters provide high flexibilitity in shape and design for operation where thermaluniformity in narrow spaces is needed for wafer fabrication.

Heater Types and Properties

Heater Type	Temperature Range	Material	Structural Formats	Power Density	Relative Cost
Ceramic AIN	Up to 650°C	AIN Tungsten	Platens or tubular	Small format 2KW/sq in 300 mm 10- 15kW Pending configuration	\$\$\$
Flexible Polyimide	-269°C to +220°C	Bonded Polyimide Layers	Flat, formed to most surfaces	40 W/sq in	\$

CERAMIC HEATERS

Fralock Ceramic heaters are made using high thermal conductivity Aluminum Nitride (AIN) ceramic with embedded Tungsten resistance heating traces, providing tailored power input to achieve your temperature transition goals.

Extremely rapid heating in excess of 300°C/sec is made possible because the coefficients of thermal expansion of Aluminum and Tungsten are the equal (4.3 x 10E-6 Co). Integrated channel structure and low density AIN ceramic provide quick cooling rates, from 300°C to room temperature in a just few seconds.



Expanded view of a rectangular heater

	Aluminum Nitride	Tungsten
Density - g/cc	3.36	19.3
Linear Coefficient of Expansion per °C	4.3 x 10 ^E -6	4.3 x 10 ^E -6
Thermal Conductivity (RT) - W/mK	180	170

Exceptional thermal uniformity and seamless transfer of temperature is achieved due to matched coefficients of thermal conductivity.

Applications Include

Front-end:

- High-temperature showerhead heaters with integrated gas flow to chamber
- Pedestal wafer heater to 650°C with and without remoted connections
- Cylindrical formats for heated nozzles, plasma generation

Back-end:

- Burn-in testing
- Class testing
- Chip stacking thermal compression bonding

FEATURES AND BENEFITS

- Multiple zones of heater and sensor traces in various levels
- Multiple resistance temperature detectors (sensors) focusing on specific locations
- Tungsten traces are fully integrated and chemically bonded into the AIN microstructure
- Tunable resistivity tungsten inks from 8-80 mOhm/square provide rapid resistance tuning for new product introduction
- Ground plane shielding
- Thin substrates: Flat, round or any geometry can be CNC milled
- · Robust reliability, proven with millions of cycles in the field
- · Complex geometry: venting, through blind features, and internal channels
- For Wafer Pedestal heaters:
 - Large Format sizes up to 380mm diameter
 - Integral stem using patented pressure-less bonding
 - Multi-zone heater and temperature sensor capability
 - Internal gas delivery passages available

ALL-POLYIMIDE HEATERS

Fralock's polyimide heaters are manufactured with fully encapsulated traces using Fralock's Adhesiveless Laminate Technology, and are more efficient, thinner, lighter, and far more durable than any comparable product on the market. Polyimide heaters offer superior performance and durability for applications in wafer fabrication equipment.

Kapton[®] Film

Etched Metal Substrate

Kapton[®] Film





Applications Include

- Gas delivery heating for non-flat requirements
- Gas box heating
- Wafer pedestal heaters for sub 250°C requirements
- Wafer Fabrication Precision Heaters (high wattage, rapid response)

Features and Benefits

- High bond strengths that exceed substrate properties
- Flammability Rating, UL[®] 94VO
- Flexible construction can be folded, wrapped, or crumpled without affecting performance
- Lightweight constructions as thin as 0.0762 mm (0.003")
- Multi-layer and multi-zone (many, independently controlled, zones of heater traces across the entire surface)
- Excellent Temperature range -269°C to +220°C
- Very low out-gassing
- Uniform and or tunable heat distribution
- Integrated sensors and flex circuits







Let us help you with your next challenging project sales@fralock.com

